

L Number	Hits	Search Text	DB	Time stamp
6	16027	"microelectromechanical system" or MEMS	USPAT; EPO; JPO; IBM_TDB	2003/04/28 08:58
7	28	(wafer and magnets and hinges) and ("microelectromechanical system" or MEMS)	USPAT; EPO; JPO; IBM_TDB	2003/04/28 08:58
8	284	(wafer or substrate) and magnets and hinges and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/04/28 10:00
9	22	(wafer or substrate) and magnets and hinges and etch\$3 and gimbal	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:06
10	49	(wafer or substrate) and magnets and hinges and gimbal	USPAT; EPO; JPO; IBM_TDB	2003/04/28 08:27
11	150	(wafer or substrate) and magnets and hinges and etch\$3 and array	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:41
12	936	((216/22) or (216/24)).CCLS.	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:42
13	62	((216/22) or (216/24)).CCLS.) and magnets	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:52
14	37	((216/22) or (216/24)).CCLS.) and (hinges or gimbal)	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:40
15	10939	magnets same (wafers or substrate)	USPAT; EPO; JPO; IBM_TDB	2003/04/28 09:50
16	21	((216/22) or (216/24)).CCLS.) and ( magnets same (wafers or substrate))	USPAT; EPO; JPO; IBM_TDB	2003/04/28 10:00
17	8	((216/22) or (216/24)).CCLS.) and micromirror	USPAT; EPO; JPO; IBM_TDB	2003/04/28 10:01
18	48	(wafer or substrate) and magnets and micromirrors	USPAT; EPO; JPO; IBM_TDB	2003/04/28 10:02